

Honeywell Electronic Materials
East 15128 Euclid Avenue, Spokane, WA 99216
Tel. (509) 252-2200 / Fax (509) 252-2278
ISO 9001/Q24 - Certified Since 1992

Honeywell
Confidential

CERTIFICATE OF COMPLIANCE AND ANALYSIS

HEM PART #: 093223

CUSTOMER: Intel Corporation
P.O. NO.: 4505519895 REL#0010
CONTRACT: 856659-10
QUANTITY: 1pc
PART NO.:
EMAIL:
NOTIFICATION:

ASSAY NO.: IN31480
LOT NO.: 4541033X21
DATE of CoFA: 11/07/2008
DATE of ORDER: 06/20/2008

DESCRIPTION: 59Ti diffusion bonded to a Cu/Zn backing plate, 300mm SIP, 20.625IN. diameter, 16.754IN. target diameter X 1.0IN. OAH Per AMAT 0190-07110 rev. 4 which has 6 additional bor holes.

CUSTOMER SPECIFICATION

HONEYWELL RESULTS

59 Ti

Trace Analysis	Spec	Actual	Source
K	< 0.01	ppm	GDMS
Li	< 0.005	ppm	GDMS
Na	< 0.01	ppm	GDMS
Al	0.04	ppm	GDMS
C	11.0000	ppm	LECO
Cr	0.1	ppm	GDMS
Cu	0.2	ppm	GDMS
Fe	1.4	ppm	GDMS
H	1.5000	ppm	LECO
Mn	0.018	ppm	GDMS
N	12.0000	ppm	LECO
Ni	0.06	ppm	GDMS
O	114.0000	ppm	LECO
S	5.0	ppm	LECO
Si	0.1	ppm	GDMS
V	0.04	ppm	GDMS
Zr	0.9	ppm	GDMS

Total Impurities

	Spec	Actual	Source
Metals	<= 10.0	2.858	ppm

Dimensional Results

	Spec	Actual	Source
CScan #E1445-X21	>= 95	100.000	%
Grain Size Average		12.10	Microns

Comments

509-252-2064
CONTRACT
PHILLIP ARIZONA
HONEYWELL.COM
(APP MAT 0190-07110-REV.4 OGM)
CONTRACT -

This product was manufactured in an ODC free environment.

This is to certify that this product conforms to the above Analysis.

Honeywell Electronic Materials
Registered To ISO 9001:2000 / TS16949
Certificate No. A9070



11/07/2008

QA REPRESENTATIVE

DATE

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CERTIFICATE OF COMPLIANCE AND ANALYSIS

HEM PART #: 093223

CUSTOMER: Intel Corporation
P.O. NO.: 4505519895 REL#0010
CONTRACT: 856659-10
QUANTITY: 1pc
PART NO.:
EMAIL
NOTIFICATION:

ASSAY NO.: IN27280
LOT NO.: 7584208X04
DATE of CofA: 11/07/2008
DATE of ORDER: 06/20/2008

DESCRIPTION: 59Ti diffusion bonded to a Cu/Zn backing plate, 300mm SIP, 20.625IN. diameter, 16.754IN. target diameter X 1.0IN. OAH Per AMAT 0190-07110 rev. 4 which has 6 additional bor holes.

CUSTOMER SPECIFICATION

HONEYWELL RESULTS

59 Ti

Trace Analysis	Spec	Actual	Source
K	< 0.01	ppm	GDMS
Li	< 0.005	ppm	GDMS
Na	< 0.01	ppm	GDMS
Al	0.13	ppm	GDMS
Cl	0.12	ppm	GDMS
Cr	0.3	ppm	GDMS
Cu	0.09	ppm	GDMS
Fe	1.4	ppm	GDMS
Mn	0.1	ppm	GDMS
Ni	0.03	ppm	GDMS
O	87.5000	ppm	LECO
S	6.0	ppm	LECO
Si	0.09	ppm	GDMS
V	0.06	ppm	GDMS
Zr	0.9	ppm	GDMS

Total Impurities	Spec	Actual	Source
Metals	<= 10.0	3.1 ppm	
Dimensional Results	Spec	Actual	Source
CScan #E1263-X04	>= 95	100.000 %	
Grain Size Average		12.10 Microns	

Comments

This product was manufactured in an ODC free environment.

This is to certify that this product conforms to the above

Analysis.

Honeywell Electronic Materials
Registered To ISO 9001:2000 / TSI6949
Certificate No. A9070

Heidi Ward

11/07/2008

QA REPRESENTATIVE

DATE

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